

OL-TFA9897C

wafer level chip-scale package; 30 bumps; 2.06 x 2.72 x 0.525 mm (Backside coating include)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP30
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-5-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.69	-	2.72	2.75	mm
E	package width	2.03	-	2.06	2.09	mm
A	seated height	0.485	-	0.525	0.565	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	30	-	



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2. Package outline

WLCSP30: wafer level chip-scale package; 30 bumps; 2.06 x 2.72 x 0.525 mm (Backside coating include) TFA9897C

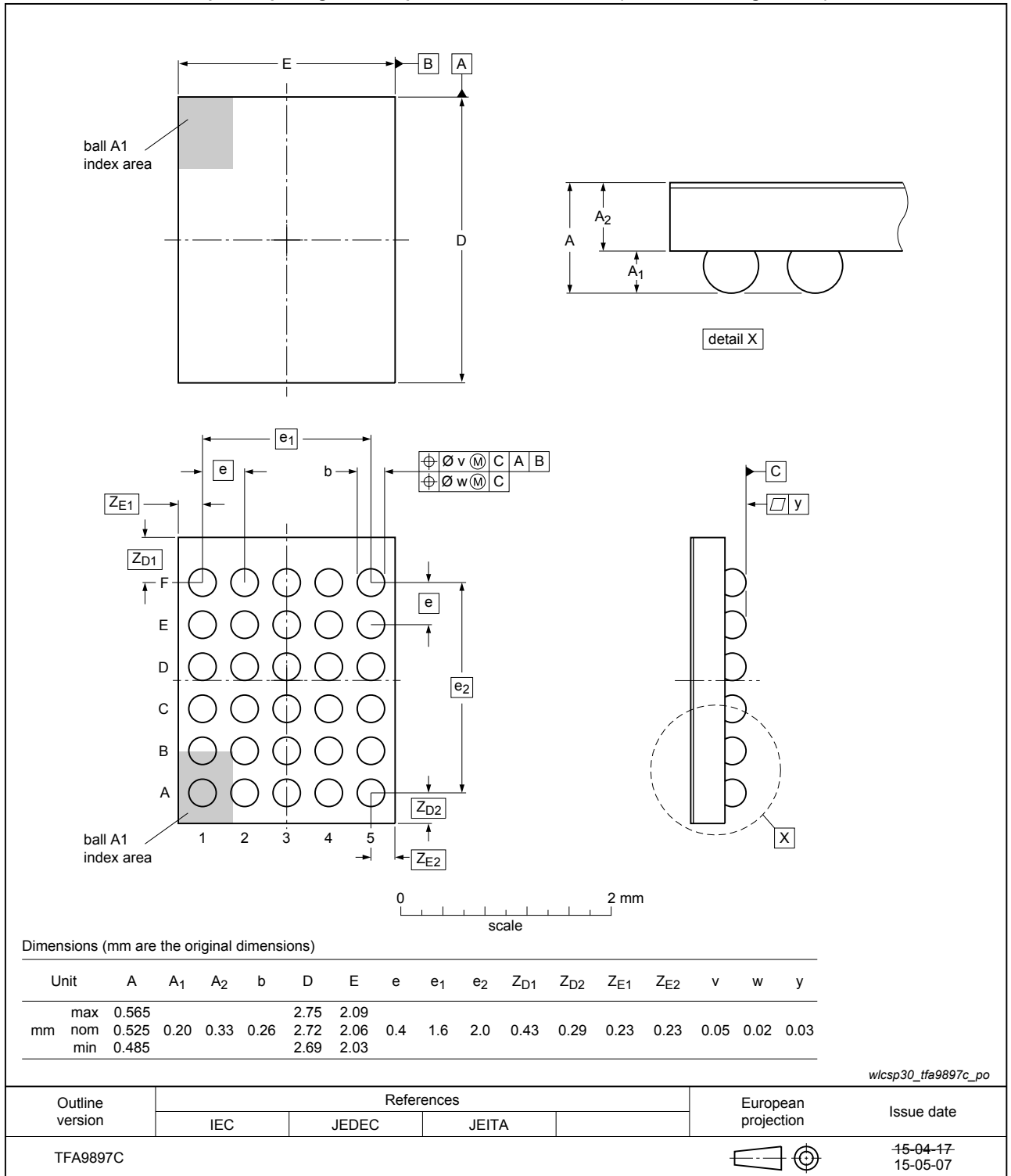


Fig. 1. Package outline WLCSP30 (OL-TFA9897C)

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3. Legal information

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